**Product End-of-Life Disassembly Instructions**

**Product Category: Notebooks**

**Marketing Name / Model**
[List multiple models if applicable.]

HP 14 Laptop PC / Andaman / OPA

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [x] screws [ ] snaps [ ] adhesive [ ] other. Explain ______.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>#0 #1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove rubber foot 2pcs.
2. Remove screw 8 pcs.
3. Disassemble the base from chassis ass'y.
4. Remove battery screw 4 pcs.
5. Remove battery pack.
6. Remove LVDS cable from MB connector.
7. Remove DB screw 2 pcs.
8. Remove USB FFC from MB & DB connector.
9. Remove antenna cable from WLAN card.
10. Remove WLAN card screw 1 pcs.
11. Remove FAN screw 3 pcs.
12. Remove Thermal module screw 4 pcs.
13. Remove FAN & Thermal module.
14. Remove WLAN card screw 1 pcs.
15. Remove SSD screw 1 pcs.
16. Remove MB screw 4 pcs.
17. Remove TP FFC from MB & TP Module.
18. Remove FPS FFC from MB & FPR moule.
19. Remove DDR module.
20. Remove DC cable from MB connector.
21. Remove LCD cable from MB connector.
22. Remove KB membrance from MB connector.

HPI instructions for this template are available at EL-MF877-01

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Last revalidation date 09-May-2018
23. Remove Speaker screw 3 pcs.
24. Remove MB.
25. Remove Speaker form MB.
26. Remove LCD module ass'y.
27. Remove FPR screw 1pcs.
28. Remove FPR BKT.
29. Remove FPR module.
30. Remove Hinge screw 4 pcs.
31. Remove TP support bracket screw 3 pcs.
32. Remove TP support bracket.
33. Remove TP holder screw 3 pcs.
34. Remove TP holder.
35. Remove LCD module ass'y
36. Remove Hinge cap.
37. Remove LCD bezel.
38. Remove panel.
39. Remove LVDS cable from panel connector.
40. Remove hinge screw 8 pcs.
41. Remove hinge.
42. Remove camera.
43. Remove antenna.
44. Remove antenna AL-foil.
45. END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module

3.23 Remove service door

N/A

3.24 LCD module set disassembly

3.25 Top case disassembly

3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly